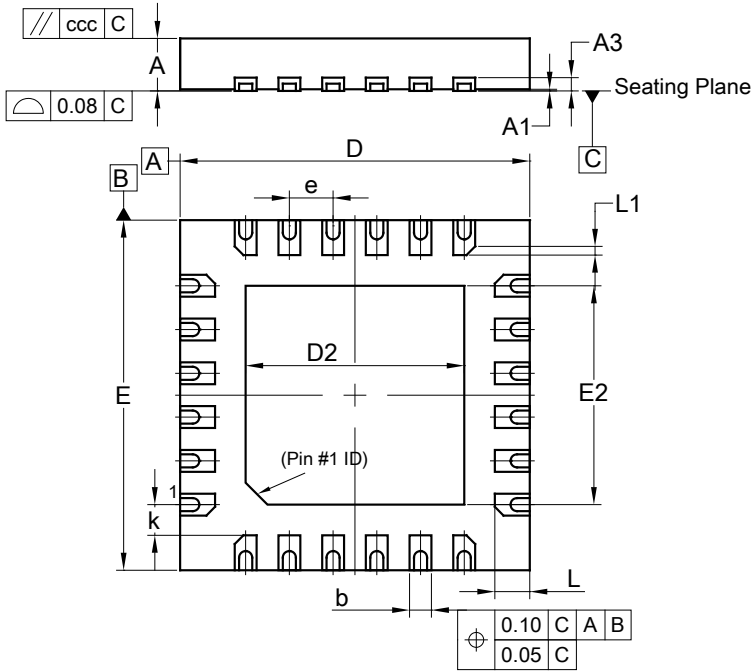


**Package Outline Dimensions**

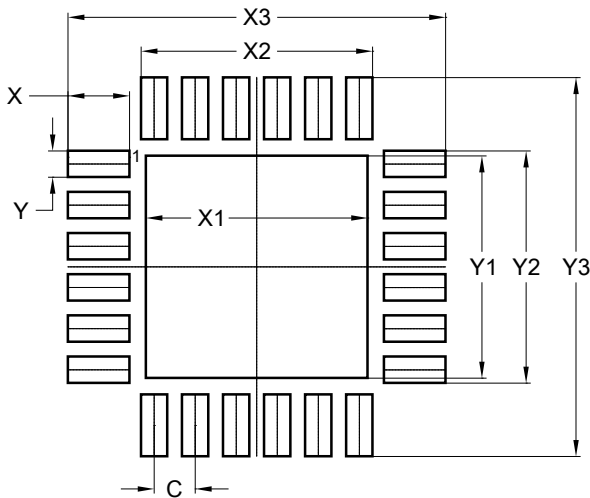
U-QFN4040-24/SWP



U-QFN4040-24/SWP			
Dim	Min	Max	Typ
A	0.55	0.65	0.60
A1	0.00	0.05	0.02
A3		0.15	REF
b	0.20	0.30	0.25
D	3.95	4.05	4.00
D2	2.40	2.60	2.50
E	3.95	4.05	4.00
E2	2.40	2.60	2.50
e		0.50	BSC
k	0.25	--	--
L	0.35	0.45	0.40
L1	0.05	0.158	0.10
All Dimensions in mm			

**Suggested Pad Layout**

U-QFN4040-24/SWP



Dimensions	Value (in mm)
C	0.050
X	0.750
X1	2.700
X2	2.820
X3	4.600
Y	0.320
Y1	2.700
Y2	2.820
Y3	4.600

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.